

101 Supp
Pre
C
PATENT Lewis
10/28/99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Norio FUKASAWA et al.

Serial No.: 09/029,608

Filed: May 15, 1998

Group Art Unit: 2812



For: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE

SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

June 4, 1999

Sir:

11/15/1999 JHCWILLA 00000007 012340 09029608

01 FC:102

78.00 Under to the Supplemental Preliminary Amendment filed on February 26, 1999, please

amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 13-17 without prejudice or disclaimer and add new claims 103-108
as follows:

C1
Cont'd

--103. A mold for fabricating a semiconductor device comprising
a first mold; and
a second mold which is located so as to face the first mold,
the second mold including a first half body having a shape corresponding to a shape of a
substrate, and a second half body which is provided so as to surround the first half body and can
be elevated with respect to the first half body,
the first and second half bodies cooperating with each other so that a cavity to be filled

RECEIVED
JUN 07 1999
TECHNOLOGY CENTER 2800